

BUK9515-100A-VB Datasheet

N-Channel 100-V (D-S) 175 °C MOSFET

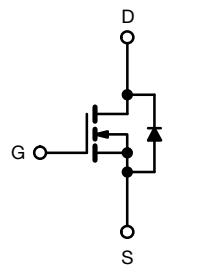
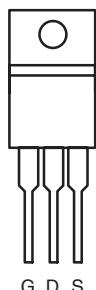
PRODUCT SUMMARY	
V_{DS} (V)	100
$R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V	0.009
$R_{DS(on)}$ (Ω) at $V_{GS} = 4.5$ V	0.020
I_D (A)	100
Configuration	Single

FEATURES

- Trench Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC



TO-220AB



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150$ °C)	I_D	100	A
$T_C = 125$ °C		75 ^a	
Pulsed Drain Current	I_{DM}	300	A
Avalanche Current	I_{AS}	75	
Single Pulse Avalanche Energy ^b	E_{AS}	280	mJ
Maximum Power Dissipation ^b	P_D	250 ^c	W
$T_C = 25$ °C (TO-220AB and TO-263)		3.75	
$T_A = 25$ °C (TO-263) ^d			
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Limit	Unit
Junction-to-Ambient	R_{thJA}	40	°C/W
Free Air (TO-220AB)		62.5	
Junction-to-Case	R_{thJC}	0.6	

Notes:

- Pulse test; pulse width ≤ 300 μ s, duty cycle ≤ 2 %.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

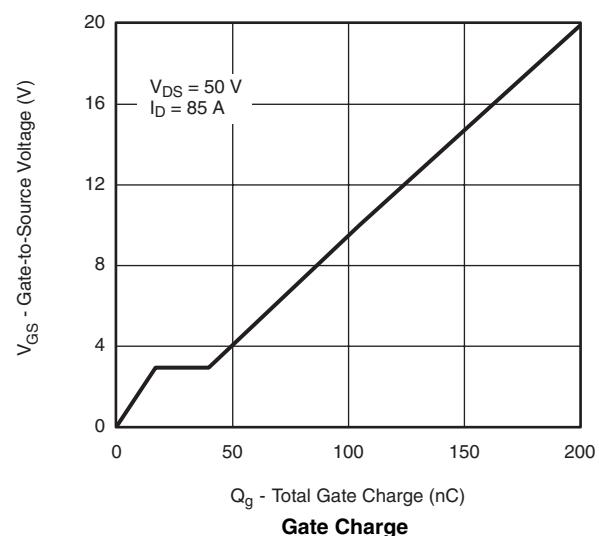
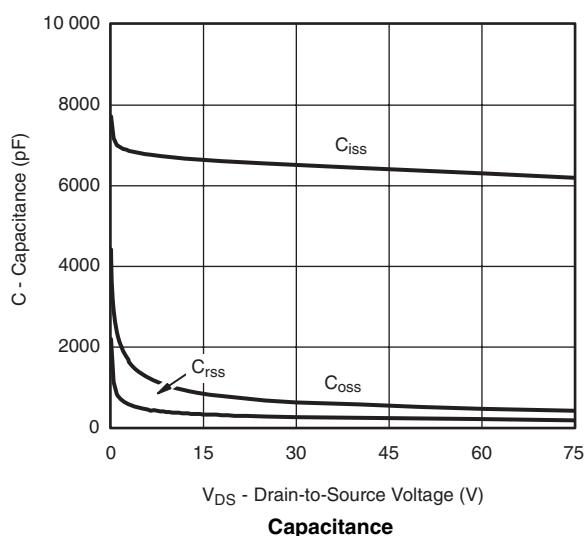
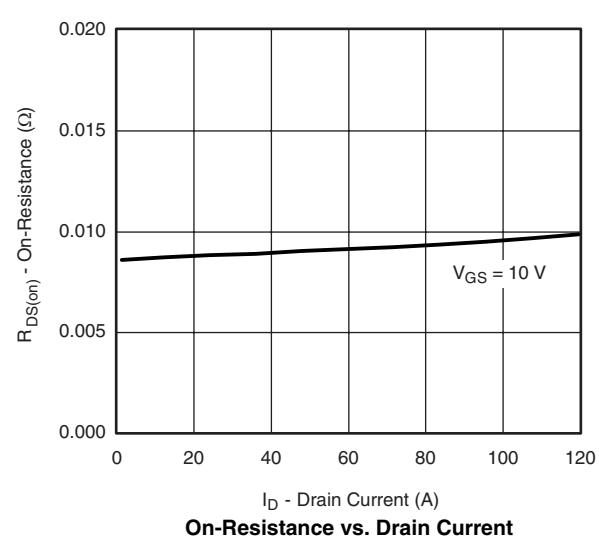
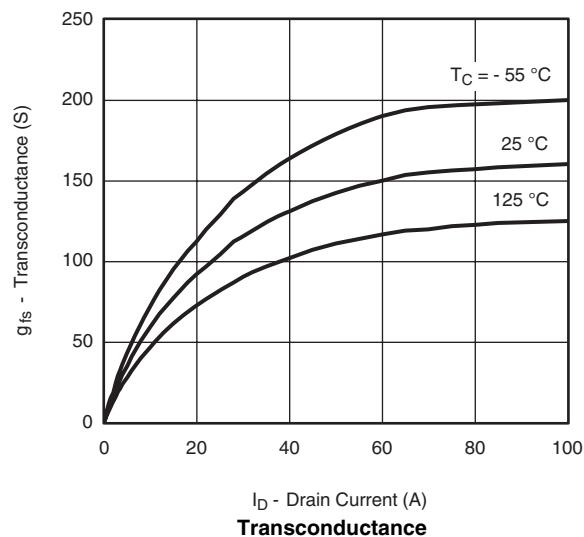
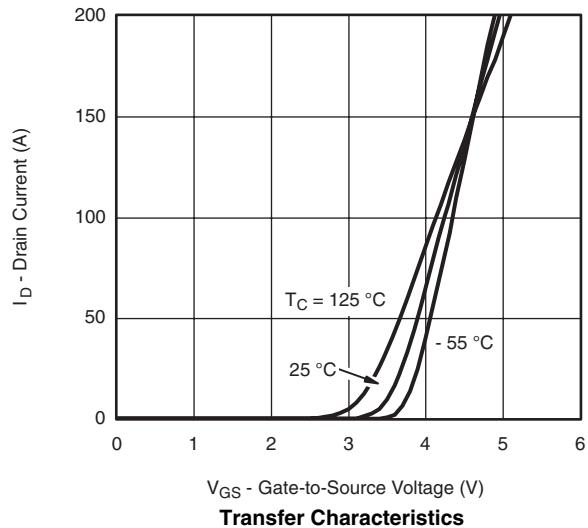
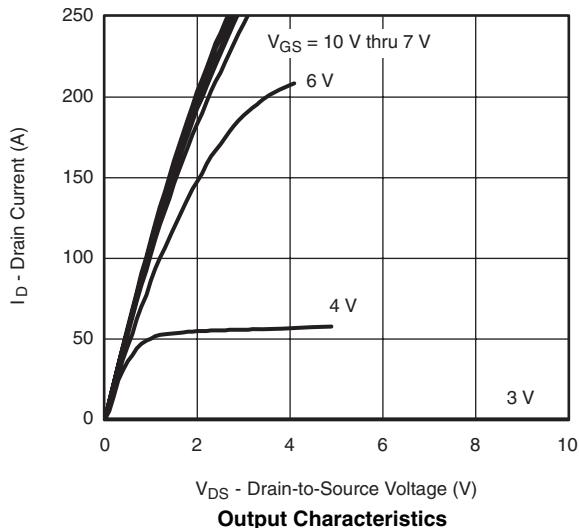
SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted

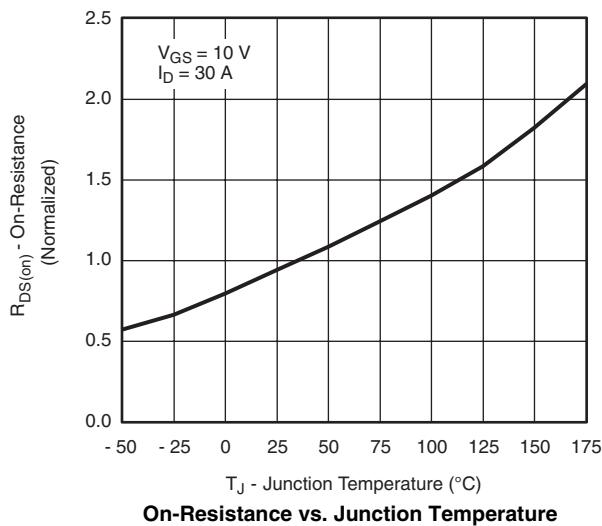
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	100			V
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2		4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}$, $V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100 \text{ V}$, $V_{GS} = 0 \text{ V}$			1	μA
		$V_{DS} = 100 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 125^\circ\text{C}$			50	
		$V_{DS} = 100 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 175^\circ\text{C}$			250	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} = \geq 5 \text{ V}$, $V_{GS} = 10 \text{ V}$	120			A
Drain-Source On-State Resistance ^a	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$, $I_D = 30 \text{ A}$		0.009		Ω
		$V_{GS} = 4.5 \text{ V}$, $I_D = 20 \text{ A}$		0.020		
		$V_{GS} = 10 \text{ V}$, $I_D = 30 \text{ A}$, $T_J = 125^\circ\text{C}$		0.023		
		$V_{GS} = 10 \text{ V}$, $I_D = 30 \text{ A}$, $T_J = 175^\circ\text{C}$		0.030		
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}$, $I_D = 30 \text{ A}$	25			S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$		4700		pF
Output Capacitance	C_{oss}			665		
Reverse Transfer Capacitance	C_{rss}			265		
Total Gate Charge ^c	Q_g	$V_{DS} = 50 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 85 \text{ A}$		105	160	nC
Gate-Source Charge ^c	Q_{gs}			17		
Gate-Drain Charge ^c	Q_{gd}			23		
Turn-On Delay Time ^c	$t_{d(\text{on})}$	$V_{DD} = 50 \text{ V}$, $R_L = 0.6 \Omega$ $I_D \geq 85 \text{ A}$, $V_{GEN} = 10 \text{ V}$, $R_g = 2.5 \Omega$		12	25	ns
Rise Time ^c	t_r			90	135	
Turn-Off Delay Time ^c	$t_{d(\text{off})}$			55	85	
Fall Time ^c	t_f			130	195	
Source-Drain Diode Ratings and Characteristics $T_C = 25^\circ\text{C}^b$						
Continuous Current	I_S				85	A
Pulsed Current	I_{SM}				240	
Forward Voltage ^a	V_{SD}	$I_F = 85 \text{ A}$, $V_{GS} = 0 \text{ V}$		1.0	1.5	V
Reverse Recovery Time	t_{rr}	$I_F = 50 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$		85	140	ns
Peak Reverse Recovery Current	$I_{RM(\text{REC})}$			4.5	7	A
Reverse Recovery Charge	Q_{rr}			0.17	0.35	μC

Notes:

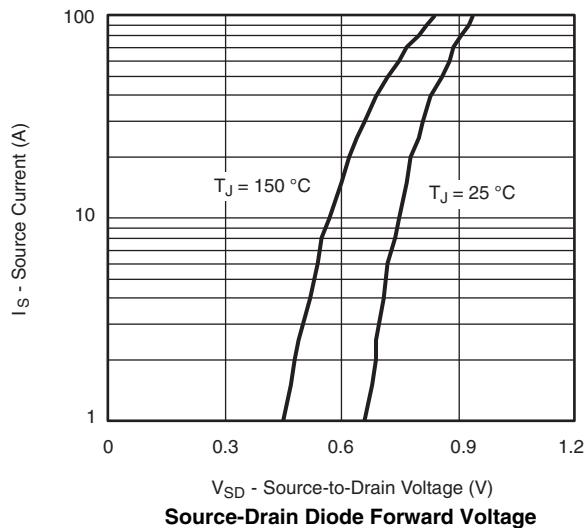
- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

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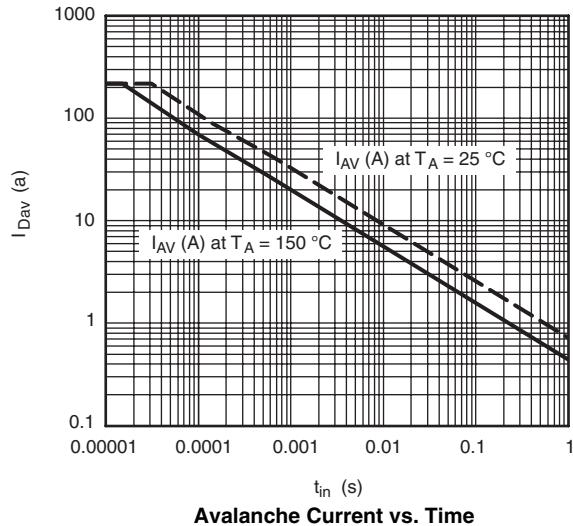
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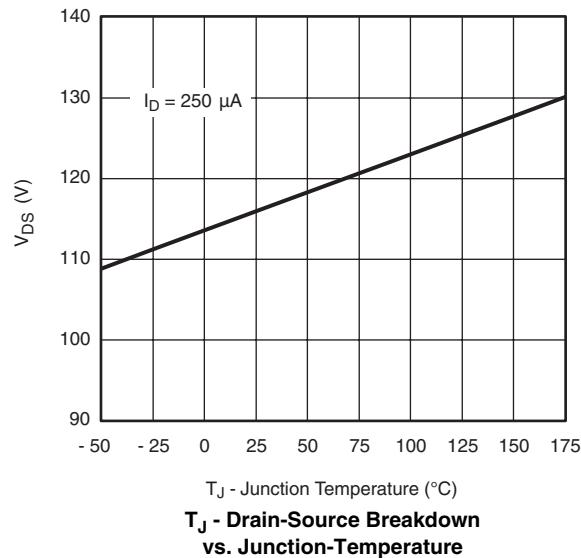
On-Resistance vs. Junction Temperature



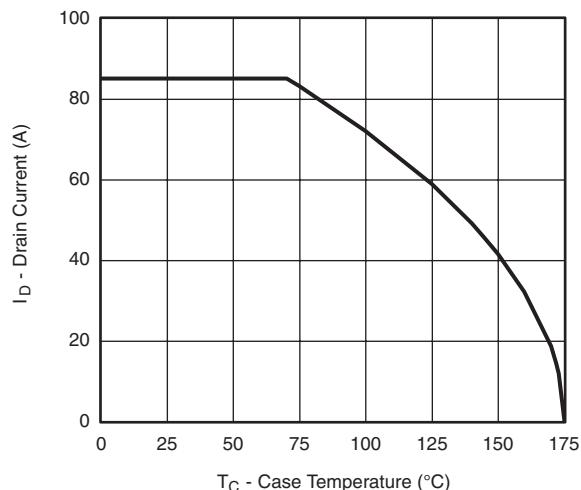
Source-Drain Diode Forward Voltage



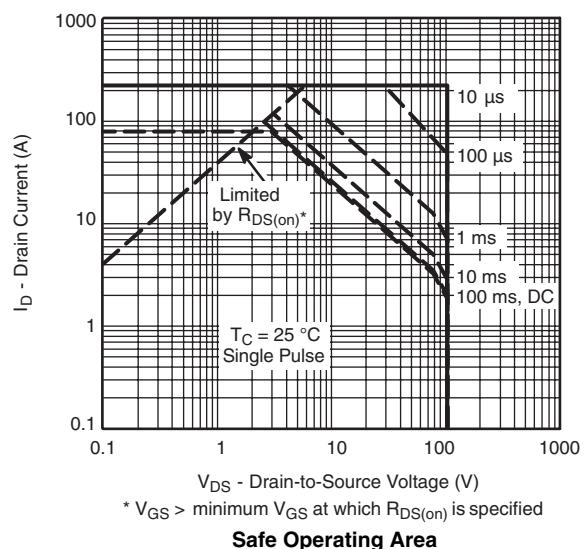
Avalanche Current vs. Time

 $T_J - \text{Drain-Source Breakdown}$
vs. Junction-Temperature

THERMAL RATINGS

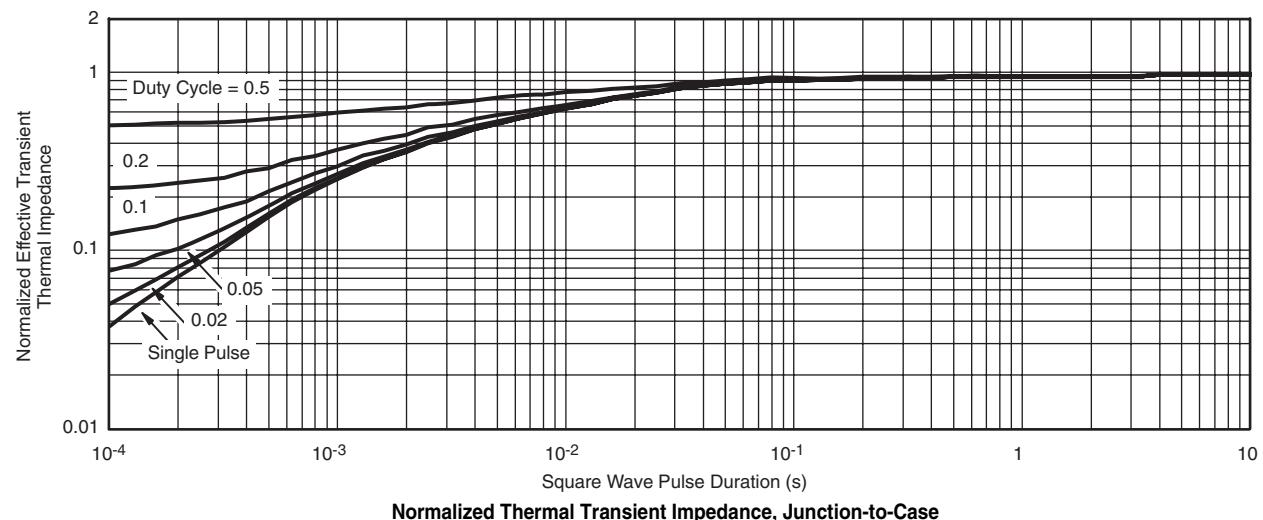


**Maximum Avalanche and Drain Current
vs. Case Temperature**



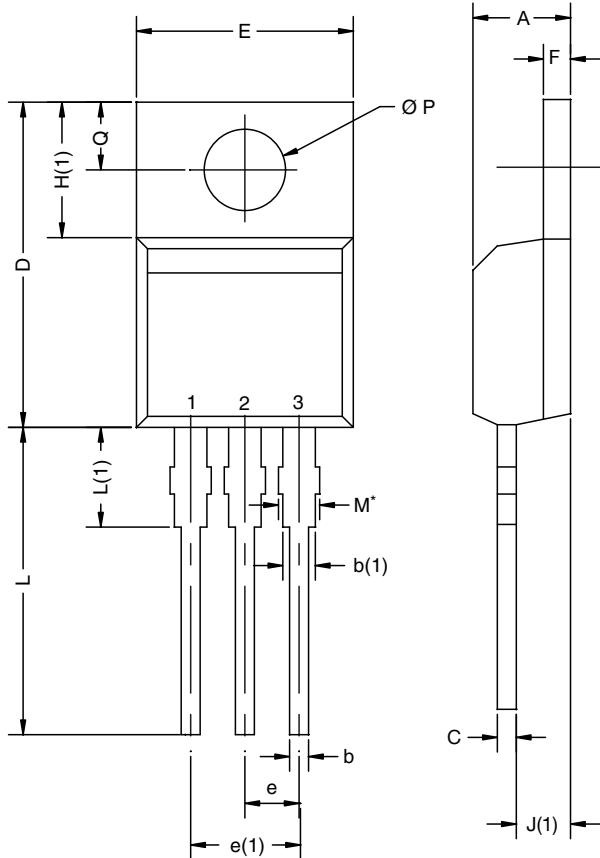
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

TO-220AB

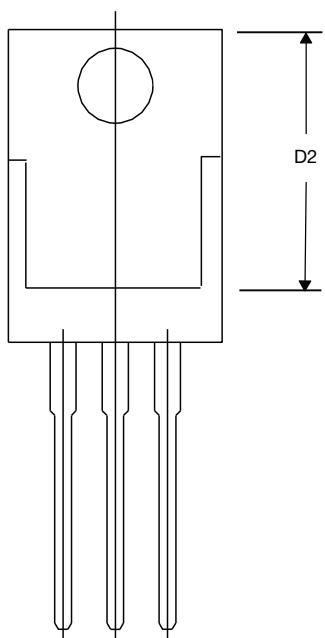


DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
c	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
Ø P	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

ECN: T14-0413-Rev. P, 16-Jun-14
 DWG: 5471

Note

* M = 1.32 mm to 1.62 mm (dimension including protrusion)
 Heatsink hole for HVM



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